

SEMICONDUCTOR COMPONENT AND METHOD OF MANUFACTURING

Abstract of the Disclosure

A semiconductor component includes a substrate (110) having a surface, a channel
5 region (120, 220) located in the substrate, a non-electrically conductive region (130)
substantially located below a substantially planar plane defined by the surface of the substrate,
a drift region (140, 240) located in the substrate and between the channel region and the non-
electrically conductive region, and an electrically floating region (150, 350, 450, 550) located
in the substrate and contiguous with the non-electrically conductive region.